

Title (en)

MEMS HAVING LID DRIVE AND METHOD FOR OPERATION THEREOF

Title (de)

MEMS MIT DECKELANTRIEB UND VERFAHREN ZUM BETREIBEN DERSELBEN

Title (fr)

MEMS PRÉSENTANT UN COUVERCLE D'ENTRAÎNEMENT ET PROCÉDÉ DE FONCTIONNEMENT ASSOCIÉ

Publication

EP 4255844 A1 20231011 (DE)

Application

EP 20820367 A 20201203

Priority

EP 2020084506 W 20201203

Abstract (en)

[origin: WO2022117197A1] The invention relates to a MEMS component comprising a layer stack having a plurality of MEMS layers arranged in a layer sequence direction. The MEMS component comprises a movable element which is formed in a first MEMS layer and is arranged between a second MEMS layer and a third MEMS layer of the layer stack. A drive device is furthermore provided and has a first drive structure, which is mechanically fixedly connected to the movable element, and a second drive structure, which is mechanically fixedly connected to the second MEMS layer. The drive device is designed to generate a drive force acting on the movable element perpendicular to the layer sequence direction, and the drive force is designed to deflect the movable element.

IPC 8 full level

B81B 3/00 (2006.01); **H02N 1/00** (2006.01); **H04R 19/00** (2006.01)

CPC (source: EP US)

B81B 3/0021 (2013.01 - EP US); **B81C 1/00198** (2013.01 - US); **H02N 1/008** (2013.01 - EP); **H04R 19/005** (2013.01 - EP); **H04R 19/02** (2013.01 - EP); **B81B 2201/0257** (2013.01 - EP US); **B81B 2201/036** (2013.01 - EP); **B81B 2201/038** (2013.01 - EP); **B81B 2203/0315** (2013.01 - US); **B81B 2203/033** (2013.01 - US); **B81B 2203/04** (2013.01 - EP US); **B81B 2203/053** (2013.01 - US); **B81B 2203/055** (2013.01 - EP); **B81C 2201/013** (2013.01 - US); **B81C 2203/032** (2013.01 - US); **B81C 2203/035** (2013.01 - US)

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

Designated validation state (EPC)

KH MA MD TN

DOCDB simple family (publication)

WO 2022117197 A1 20220609; CN 116802143 A 20230922; EP 4255844 A1 20231011; TW 202235359 A 20220916; US 2023322546 A1 20231012

DOCDB simple family (application)

EP 2020084506 W 20201203; CN 202080108389 A 20201203; EP 20820367 A 20201203; TW 110145086 A 20211202; US 202318328129 A 20230602